



Mini-Circuits

THIN FILM SURFACE MOUNT

Bandpass Filter

ABF-9R3G+

50Ω

9.2 to 9.4GHz

KEY FEATURES

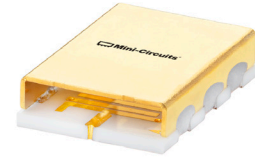
- Low Passband Insertion Loss of 1.2 dB Typ.
- High Rejection of 53 dB Typ.
- Good Return Loss of 15 dB Typ.
- Small Size, 5.59 x 8.13 x 2.03 mm

APPLICATIONS

- Phased Array SATCOM Antenna
- Ground Antenna for weather satellites both commercial & military
- Test and Measurement Equipment

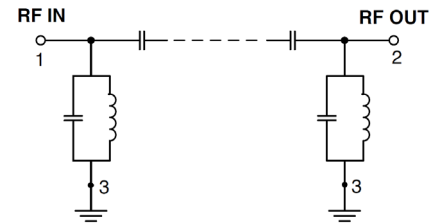
PRODUCT OVERVIEW

Mini-Circuits' Surface Mount Thin-Film filters offer low insertion loss and high rejection realized via Thin-Film on Alumina substrate, using a sputtering process that can guarantee an enhanced Q and repeatable performance. Low pass, high pass, and bandpass surface mount thin-film designs can be realized with this technology up to 40 GHz in a small form factor helping customers achieve their SWaP objectives. Using our high quality thin-film manufacturing process we can guarantee repeatability on large batches of filters.



Generic photo used for illustration purposes only

FUNCTIONAL DIAGRAM

ELECTRICAL SPECIFICATIONS^{1,2,3} AT +25°C

Parameter		F#	Frequency (GHz)	Min.	Typ.	Max.	Units
Pass Band	Center Frequency ⁴	—	—	—	9.3	—	GHz
	Insertion Loss	F1-F2	9.2 - 9.4	—	1.2	2.4	dB
	Return Loss	F1-F2	9.2 - 9.4	—	15	—	dB
Stopband, Lower	Rejection	DC-F3	DC - 6.5	43	53	—	dB
		F3-F4	6.5 - 7.8	20	35	—	
Stopband, Upper	Rejection	F5-F6	10.7 - 12	20	32	—	dB
		F6-F7	12 - 17	33	42	—	
		F7-F8	17 - 19	—	30	—	

1. Tested in Evaluation Board P/N TB-ABF-9R3G+ with feedline losses removed by normalization of S12 and S21 traces to measurement of TB thru-line.

2. This filter is bi-directional RF1 and RF2 ports may be interchanged, see S-Parameters for actual performance.

3. This component is not intended for use as a DC-blocking circuit element. In applications where DC voltage and/or current is present at either the input or output ports, external DC blocking capacitors are required.

4. Typical variation $\pm 3\%$.

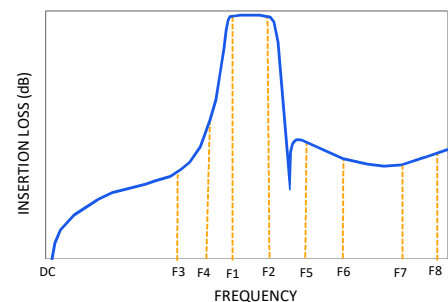
ABSOLUTE MAXIMUM RATINGS⁵

Parameter	Ratings
Operating Temperature	-55 °C to +125 °C
Storage Temperature	-55 °C to +125 °C
Input Power ⁶	1W Max. at 25°C

5. Permanent damage may occur if any of these limits are exceeded.

6. Power rating applies only to signals within the passband.

TYPICAL FREQUENCY RESPONSE AT +25°C



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REV. A
ECO-024318
ABF-9R3G+
EDU4429
URJ
250127

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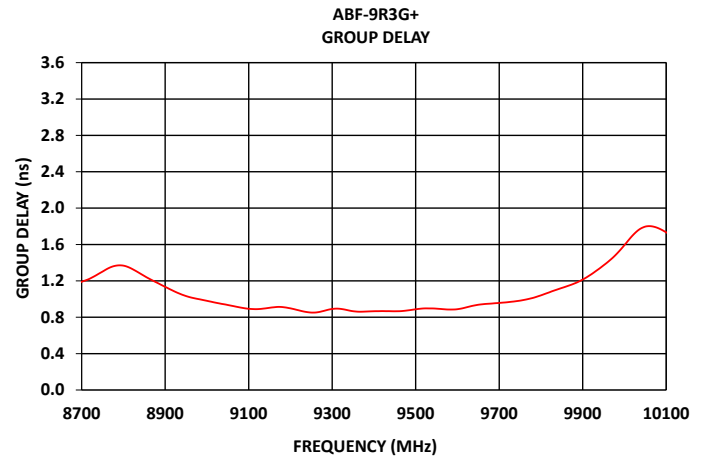
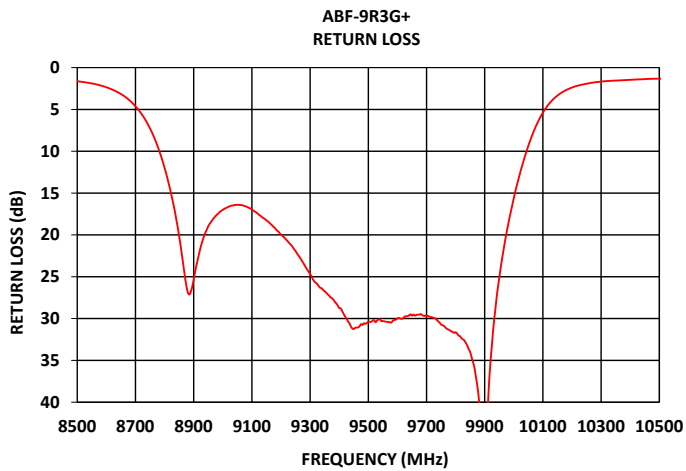
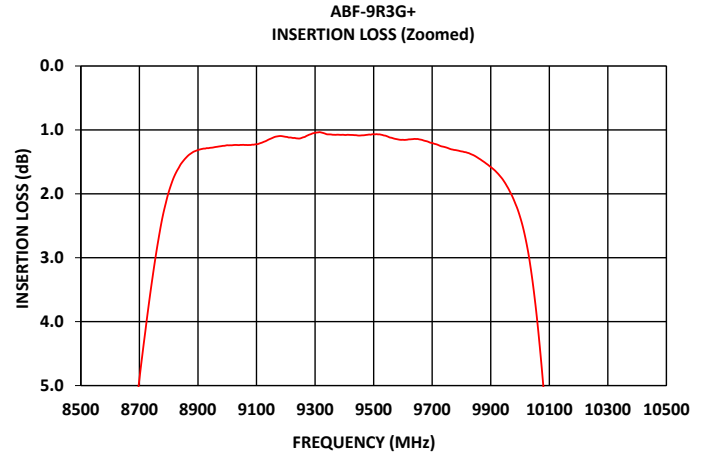
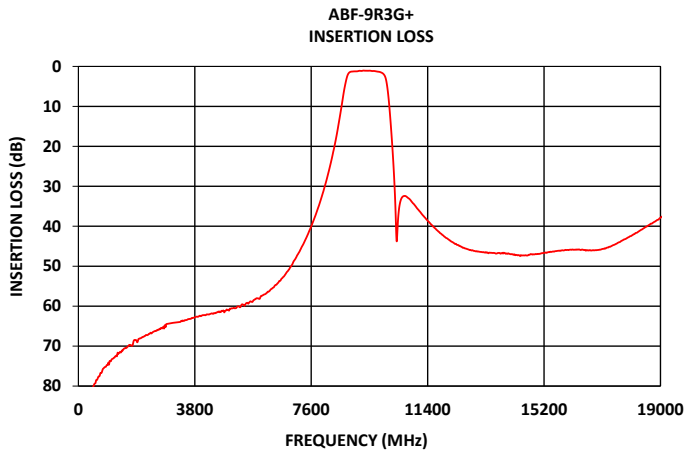
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TYPICAL PERFORMANCE GRAPHS AT +25°C





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FUNCTIONAL DIAGRAM

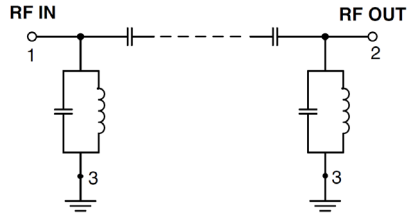
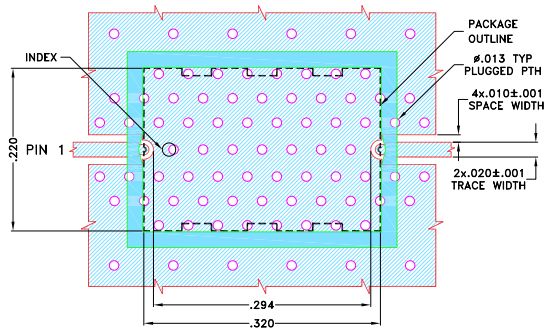


Figure 1. ABF-9R3G+ Functional Diagram

PAD DESCRIPTION

Function	Pad Number	Description
RF1 ²	1	Connects to RF Input Port
RF2 ²	2	Connects to RF Output Port
GROUND	3	Connects to Ground on PCB, (See drawing PL-652)
NC	—	No connection, not used internally. See drawing PL-652 for connection to PCB

SUGGESTED PCB LAYOUT (PL-652)

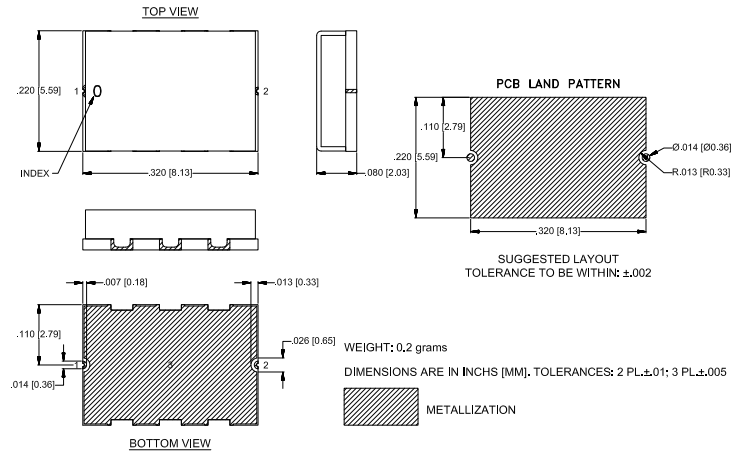


NOTES:

1. COPLANAR WAVEGUIDE PARAMETERS ARE SHOWN FOR ROGERS (R04350B) WITH DIELECTRIC THICKNESS .010±.0010. COPPER: 1/2 Oz. EACH SIDE. FOR OTHER MATERIALS TRACE WIDTH AND GAP MAY NEED TO BE MODIFIED.
 2. BOTTOM SIDE OF THE PCB IS CONTINUOUS GROUND PLANE.
- DENOTES PCB COPPER PATTERN WITH SMOBC (SOLDER MASK OVER BARE COPPER)
 DENOTES PCB COPPER PATTERN FREE OF SOLDERMASK

Figure 2. Suggested PCB Layout PL-652

CASE STYLE DRAWING



PRODUCT MARKING*: ABF-9R3G

*Marking may contain other features or characters for internal lot control.



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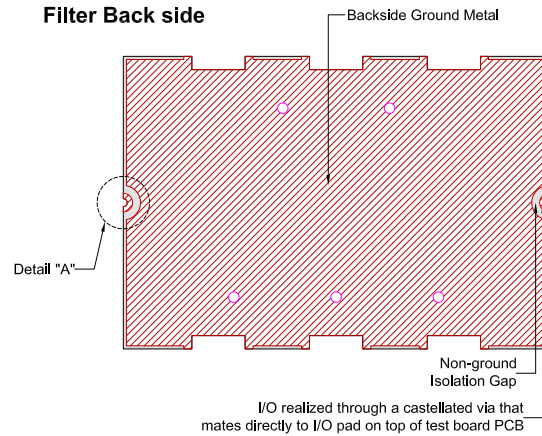
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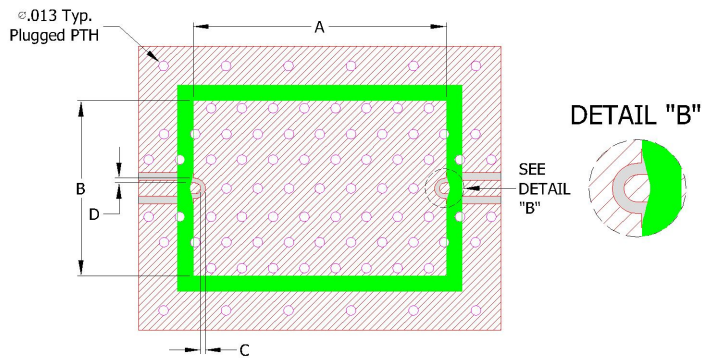
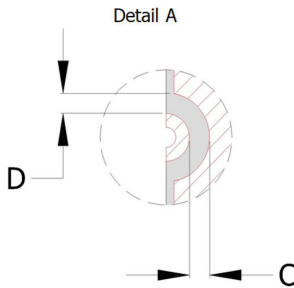
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RECOMMENDED PCB LAYOUT PATTERN FOR FILTER



PCB Pattern Recommendations

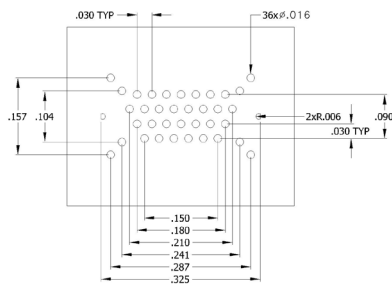
Filter RF I/O Detail
(Filter Back Side)

- 1) Customer PCB's ground pattern length (dimension A) can be similar to filter length.
- 2) Customer PCB's ground pattern width (dimension B) can be similar to filter width.
- 3) Dimensions C and D on Filter RF I/O detail and Customer PCB pattern can be closely match. The dimensions of C and D on the Customer PCB pattern can be slightly larger to account for component alignment tolerance (ground metal can be pulled back from RF I/O trace).
- 4) Recommend to use Solder mask at Customer PCB at outer area of filter pattern/ footprint with a clearance of about 1.25mil at each side. (Tighter registration tolerance required for solder mask)
- 5) Recommended to use Solder mask at I/O of Customer PCB as per above diagram (refer detail B).

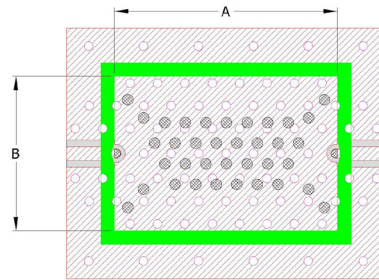
**COMMENTS ON COMPONENT HANDLING AND SOLDER ATTACH**

- 1) Avoid using soldering iron directly to the ceramic filter. This would lead to development of crack in the component due to thermal shock.
- 2) Vacuum pick-up tool or plastic tweezers are recommended for handling the components. Extra care should be taken not to scratch the filter or metal area.
- 3) Use 2-3 mil thickness stencil plate and screen print the solder. Refer below picture for recommended stencil pattern to get the best solder attachment.

Stencil opening drawing



Solder location after screen print



- 4) Plugged ground vias in the PWB will improve attachment consistency.
- 5) Recommended to have a similar or closer test board material and thickness (refer Mini-Circuits evaluation board for details) to minimize the CTE over the temperature range.



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ADDITIONAL DETAILED INFORMATION IS AVAILABLE ON OUR DASHBOARD.

[CLICK HERE](#)

Performance Data and Graphs	Data
	Graphs
	S-Parameter (S2P Files) Data Set (.zip file) De-embedded to device pads
Case Style	UC2731 Lead Finish: Gold over Nickel plate
RoHS Status	Compliant
Tape and Reel	TR-F003
Suggested Layout for PCB Design	PL-652
Evaluation Board	TB-ABF-9R3G+
	Gerber File
Environmental Rating	ENV120

NOTES

- A. Performance and quality attributes and conditions not expressly stated in this specification document are intended to be excluded and do not form a part of this specification document.
- B. Electrical specifications and performance data contained in this specification document are based on Mini-Circuits' applicable established test performance criteria and measurement instructions.
- C. The parts covered by this specification document are subject to Mini-Circuits' standard limited warranty and terms and conditions (collectively, "Standard Terms"); Purchasers of this part are entitled to the rights and benefits contained therein. For a full statement of the standard terms and the exclusive rights and remedies thereunder, please visit Mini-Circuits' website at www.minicircuits.com/terms/viewterm.html

